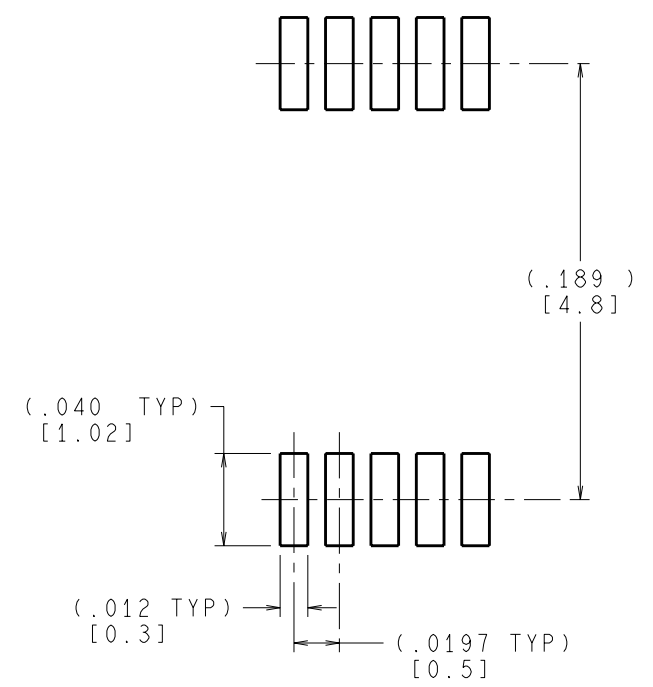
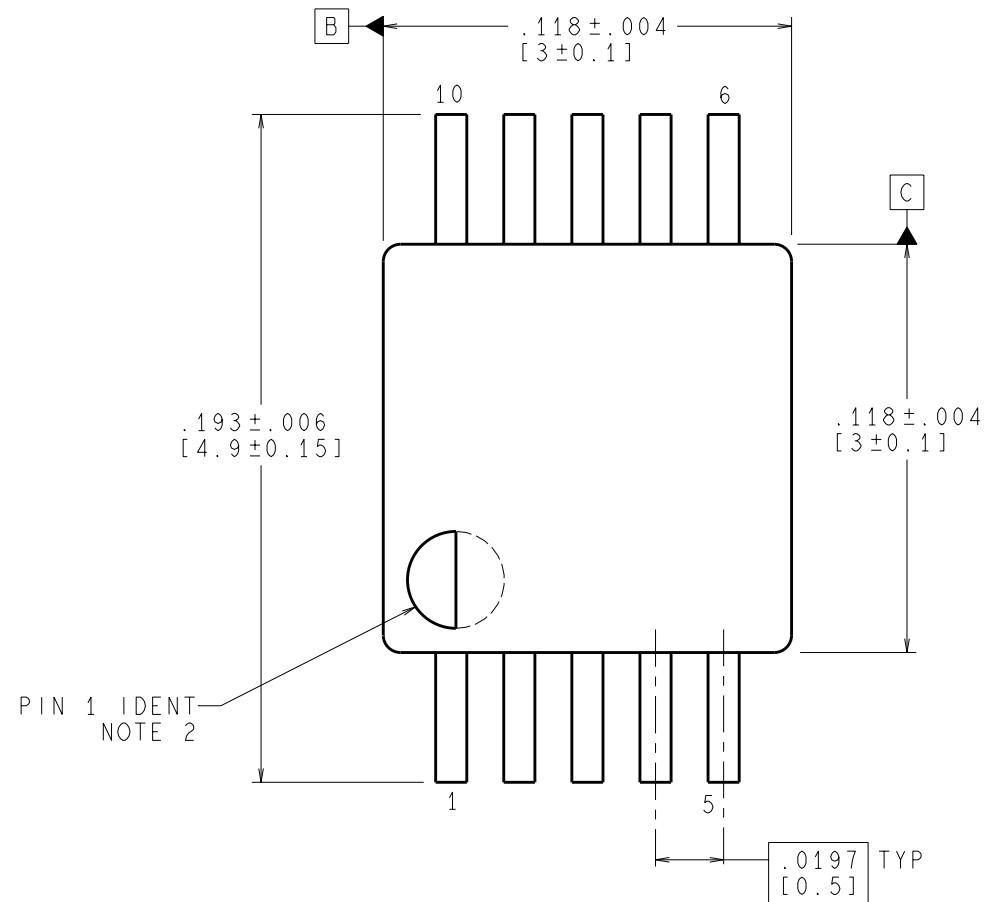
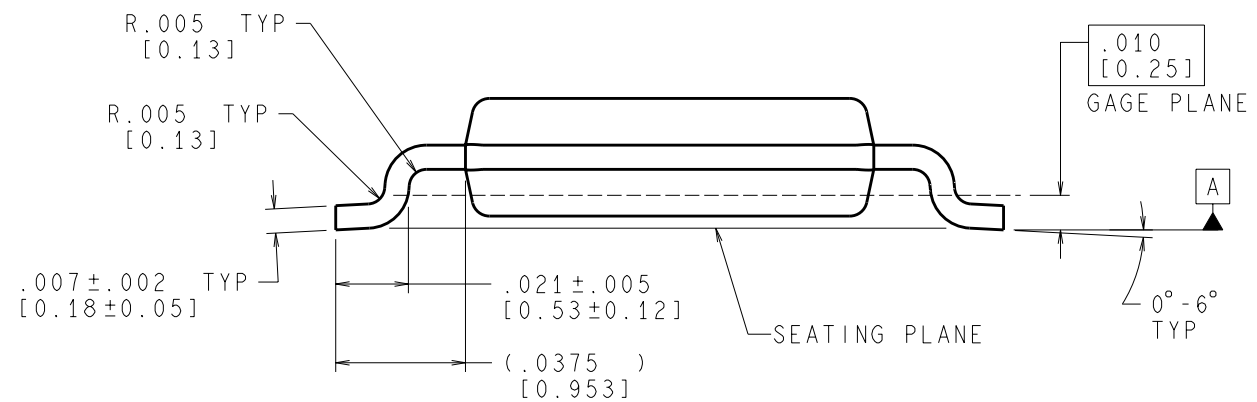
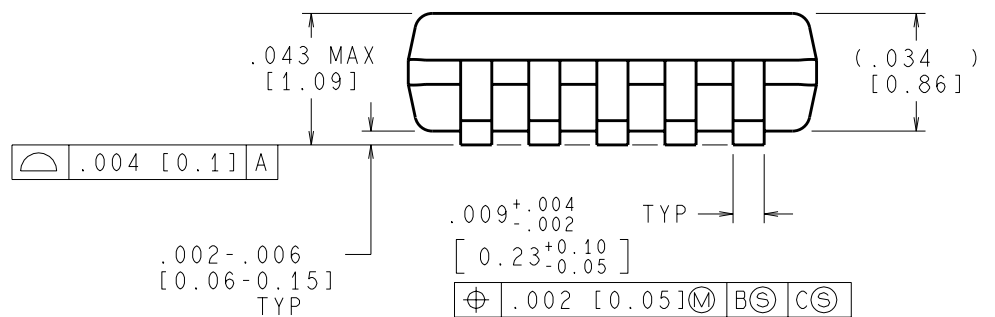


REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	12417	02/24/2000	SN/MS/JJY



**LAND PATTERN RECOMMENDATION**



**CONTROLLING DIMENSION IS INCH  
VALUES IN [ ] ARE MILLIMETERS**

NOTES: UNLESS OTHERWISE SPECIFIED

- STANDARD LEAD FINISH TO BE 200 MICROINCHES/ 5.08 MICROMETERS MINIMUM TIN/LEAD (SOLDER) ON COPPER.
- PIN 1 IDENTIFICATION TO HAVE HALF OR FULL CIRCLE OPTION.
- NO JEDEC REGISTRATION AS OF FEB 2000.

APPROVALS	DATE	National Semiconductor		
DRAWN N. SANTHIRAN	02/24/2000	2900 Semiconductor Dr., Santa Clara, CA 95052-8090		
DFTG. CHK. THANH LEQUANG	02/24/2000	<b>MOLDED PACKAGE, MINI-SO, .118in WIDE, 10 LEAD, .0197in PITCH</b>		
ENGR. CHK. JJ YEOH	02/24/2000			
PROJECTION	SCALE	SIZE	DRAWING NUMBER	REV
	N/A	C	(SC)MKT-MUB10A	A
INCH [MM]	FORMERLY: N/A	SHEET 1 of 1		